

***In The Claims***

Please cancel claims 19-21 without a disclaimer or prejudice thereto.

Please amend claim 18, as follows. The "marked-up" version of the amended claims are provided in the APPENDIX attached hereafter.

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18. (Amended) An apparatus for depositing a layer on a substrate, comprising:  
a load lock chamber receiving a substrate having a gate wire pattern formed thereon;  
a preheat chamber receiving the substrate from said load lock chamber and heating the substrate before deposition;  
a deposition chamber depositing a gate insulating layer, an amorphous silicon layer and a doped amorphous silicon layer by chemical vapor deposition; and  
a sputter chamber depositing a metal layer on the doped amorphous silicon layer by sputtering,  
wherein the substrate is transferred from said deposition chamber to said sputter chamber in a vacuum.

**REMARKS**

In response to the Office Action dated July 5, 2002, claims 19-21 have been cancelled, and claim 18 has been amended. Claim 18 is the only active claim in this application

Entry of the Amendments and Remarks is respectfully requested because entry of Amendment places the present application in condition for allowance, or in the alternative, better form for appeal. No new matters are believed to be added by this Amendments. Based on the